

SOT343N

plastic surface-mounted package; 4 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO4
Package type industry code	SO4
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.8	-	2	2.2	mm
E	package width	1.15	-	1.25	1.35	mm
A	seated height	0.8	-	0.95	1.1	mm
n ₂	actual quantity of termination	-	-	4	-	



2. Package outline

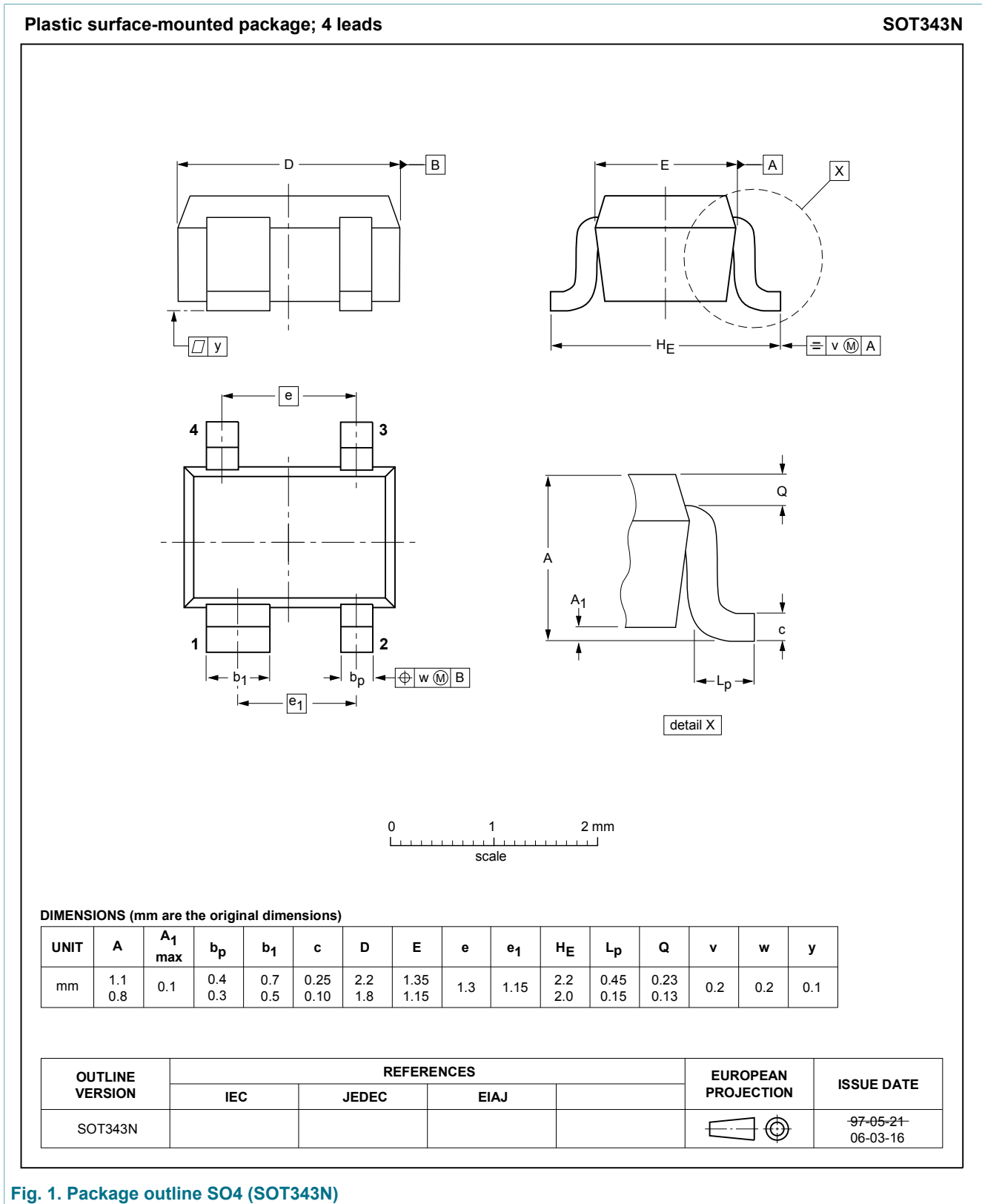


Fig. 1. Package outline SO4 (SOT343N)

3. Soldering

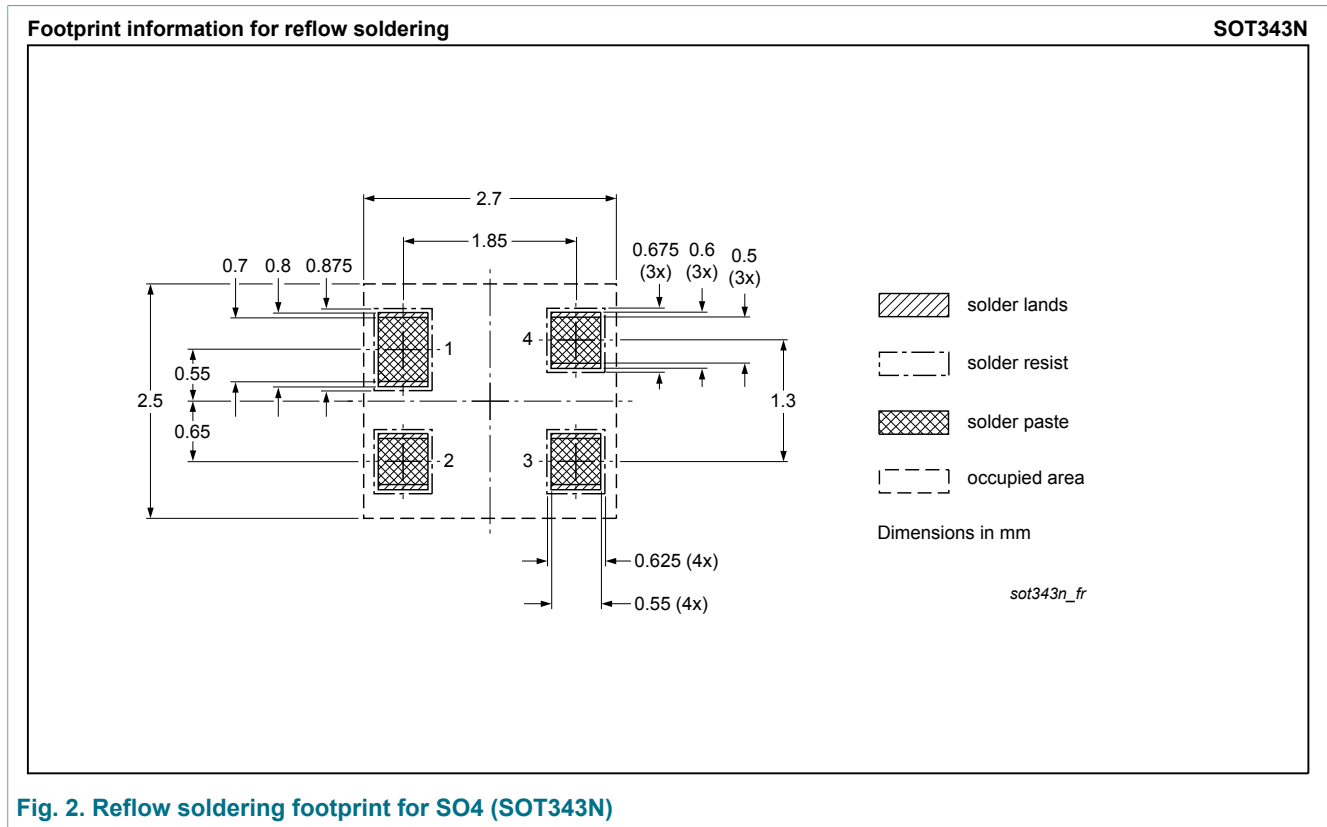


Fig. 2. Reflow soldering footprint for SO4 (SOT343N)

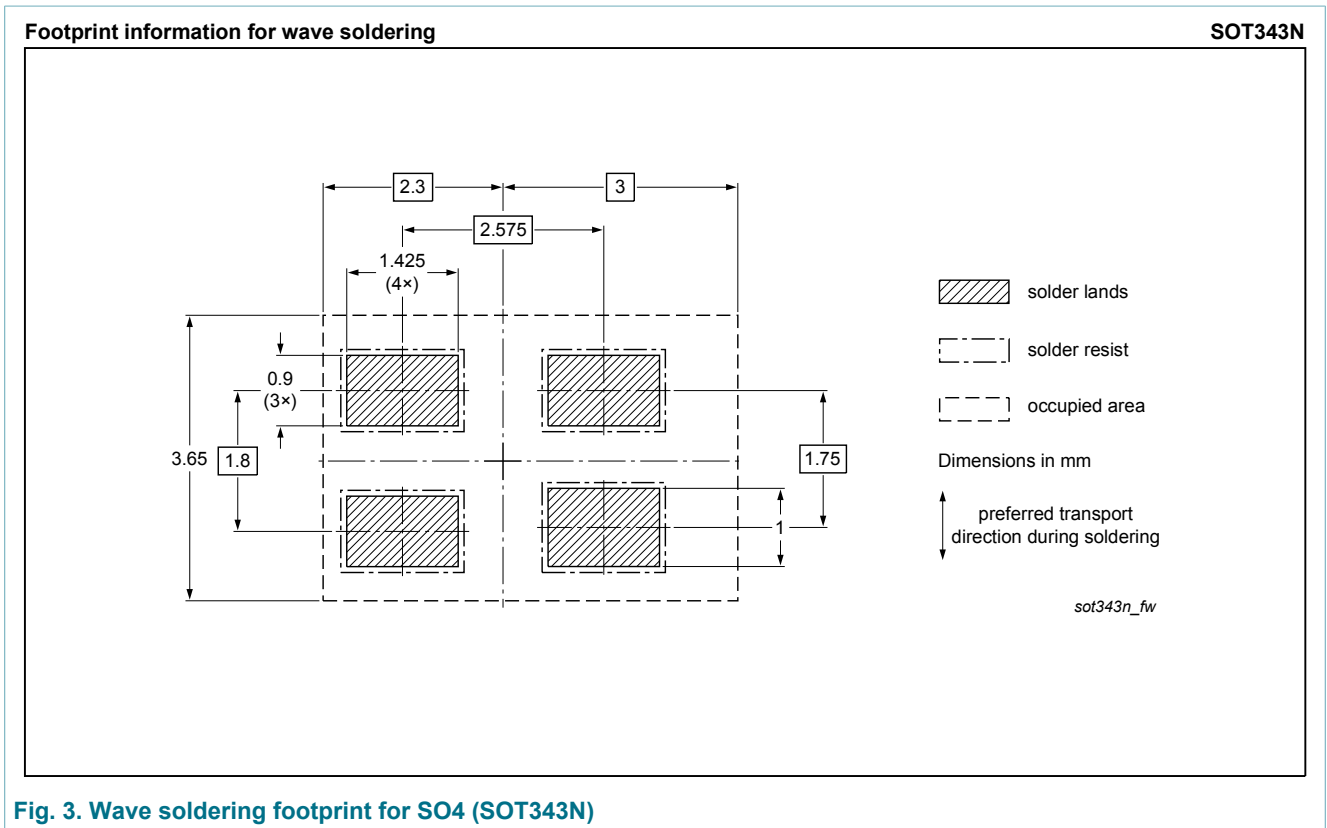


Fig. 3. Wave soldering footprint for SO4 (SOT343N)

4. Legal information

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